RECTRON SEMICONDUCTOR
TECHNICAL SPECIFICATION

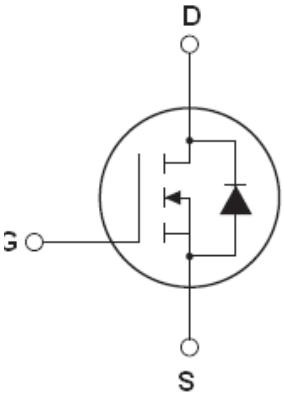
RM12N650LD
RM12N650IP

N-Channel Super Junction Power MOSFET Ⅲ

General Description

The series of devices use advanced trench gate super junction technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

V_{DS}	650	V
$R_{DS(ON)TYP}$	290	mΩ
I_D	11.5	A



Schematic diagram

Features

- New technology for high voltage device
- Low on-resistance and low conduction losses
- Small package
- Ultra Low Gate Charge cause
- 100% Avalanche Tested
- ROHS compliant

Application

- Power factor correction（PFC）
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply（UPS）

Package Marking And Ordering Information

Device	Device Package	Marking
RM12N650LD	TO-252	12N650
RM12N650IP	TO-251	12N650

TO -252

TO -251

Table 1. Absolute Maximum Ratings (T_C=25℃)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (V_{GS}=0V)	V_{DS}	650	V
Gate-Source Voltage (V_{DS}=0V) AC (f>1 Hz)	V_{GS}	±30	V
Continuous Drain Current at T_C =25°C	$I_{D\ (DC)}$	11.5	A
Continuous Drain Current at T_C=100°C	$I_{D\ (DC)}$	7	A
Pulsed drain current **(Note 1)**	$I_{DM\ (pluse)}$	46	A
Maximum Power Dissipation(T_C =25℃)	P_D	101	W
Derate above 25°C		0.97	W/°C
Single pulse avalanche energy **(Note2)**	E_{AS}	144	mJ
Avalanche current **(Note 1)**	I_{AR}	6	A
Repetitive Avalanche energy ,t_{AR} limited by T_{jmax} **(Note 1)**	E_{AR}	0.5	mJ

Parameter	Symbol	Value	Unit
Drain Source voltage slope, V_{DS} ≤480 V,	dv/dt	50	V/ns
Reverse diode dv/dt， V_{DS} ≤480 V,I_{SD}<I_D	dv/dt	15	V/ns
Operating Junction and Storage Temperature Range	T_J,T_{STG}	-55...+150	°C

Table 2. Thermal Characteristic

Parameter	Symbol	Value	Unit
Thermal Resistance，Junction-to-Case（Maximum）	R_{thJC}	1.24	°C /W
Thermal Resistance，Junction-to-Ambient （Maximum）	R_{thJA}	62	°C /W

Table 3. Electrical Characteristics (TA=25℃unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
On/off states						
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V I_D=250μA	650			V
Zero Gate Voltage Drain Current(Tc=25℃)	I_{DSS}	V_{DS}=650V,V_{GS}=0V			1	μA
Zero Gate Voltage Drain Current(Tc=125℃)	I_{DSS}	V_{DS}=650V,V_{GS}=0V			100	μA
Gate-Body Leakage Current	I_{GSS}	V_{GS}=±20V,V_{DS}=0V			±100	nA
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS},I_D=250μA	3	3.5	4	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	V_{GS}=10V, I_D=7A		290	360	mΩ
Dynamic Characteristics						
Input Capacitance	C_{lss}	V_{DS}=50V,V_{GS}=0V, F=1.0MHz		870		pF
Output Capacitance	C_{oss}			54		pF
Reverse Transfer Capacitance	C_{rss}			1.8		pF
Total Gate Charge	Q_g	V_{DS}=480V,I_D=11.5A, V_{GS}=10V		19		nC
Gate-Source Charge	Q_{gs}			6		nC
Gate-Drain Charge	Q_{gd}			6.5		nC
Switching times						
Turn-on Delay Time	$t_{d(on)}$	V_{DD}=380V,I_D=5.8A, R_G=3Ω,V_{GS}=10V		11		nS
Turn-on Rise Time	t_r			8		nS
Turn-Off Delay Time	$t_{d(off)}$			58	70	nS
Turn-Off Fall Time	t_f			9	14	nS
Source- Drain Diode Characteristics						
Source-drain current(Body Diode)	I_{SD}	T_C=25°C			11.5	A
Pulsed Source-drain current(Body Diode)	I_{SDM}				46	A
Forward on voltage	V_{SD}	Tj=25°C,I_{SD}=11.5A,V_{GS}=0V		0.9	1.2	V
Reverse Recovery Time	t_{rr}	Tj=25°C,I_F=5.8A, di/dt=100A/μs		220		nS
Reverse Recovery Charge	Q_{rr}			2.2		uC
Peak Reverse Recovery Current	I_{rrm}			19		A

Notes: 1.Repetitive Rating: Pulse width limited by maximum junction temperature

2. Tj=25℃,VDD=50V,VG=10V, R_G=25Ω

RATING AND CHARACTERISTICS CURVES (RM12N650LD(IP))

Figure1. Safe operating area

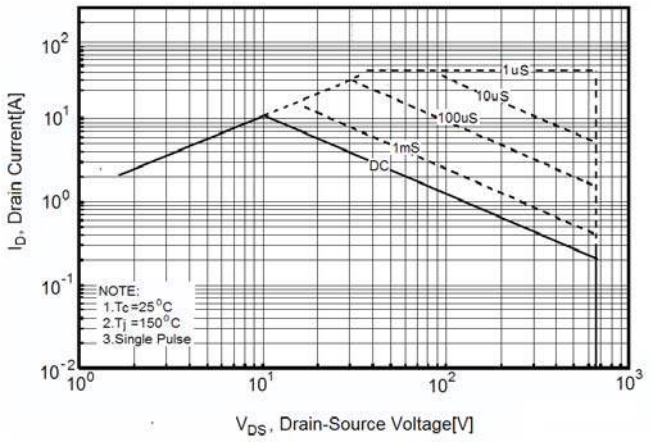


Figure2. Transient Thermal Impedance

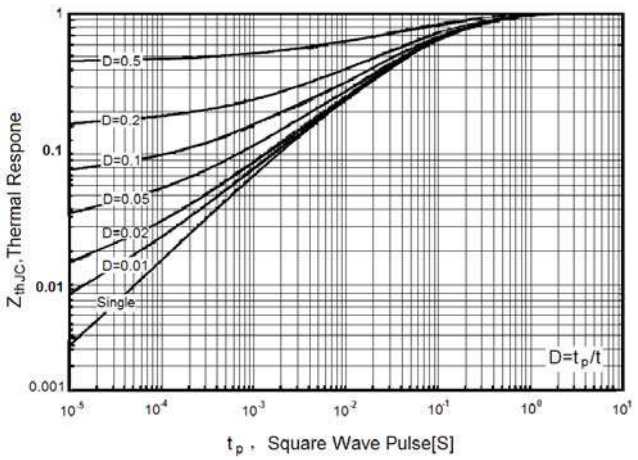


Figure3. Source-Drain Diode Forward Voltage

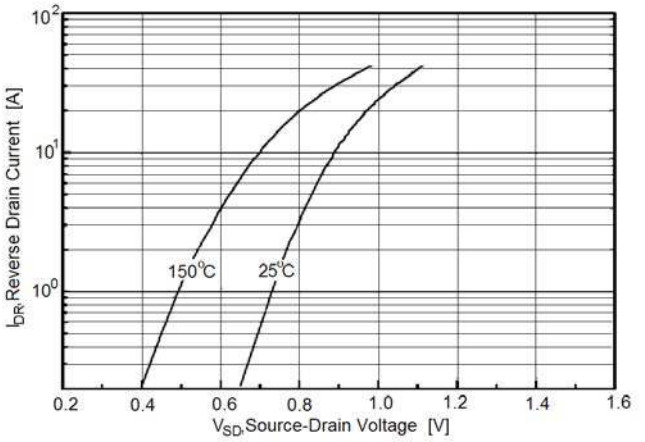


Figure4. Output characteristics

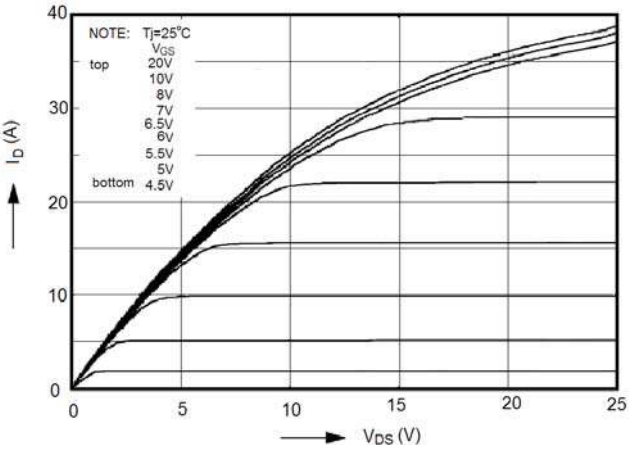


Figure5. Transfer characteristics

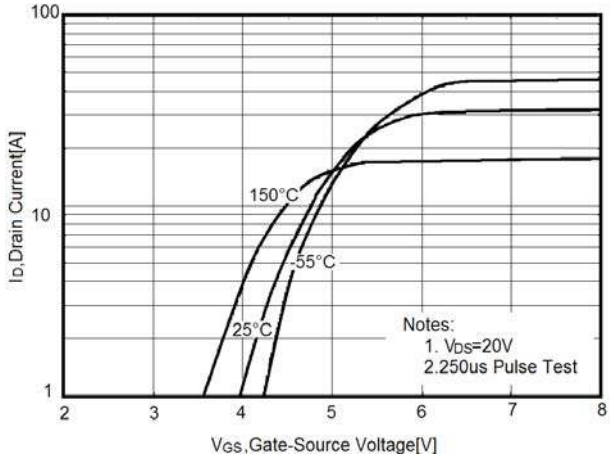
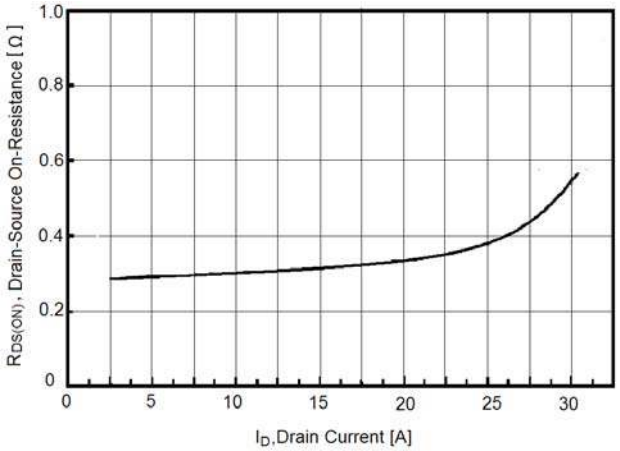


Figure6. Static drain-source on resistance



RATING AND CHARACTERISTICS CURVES (RM12N650LD(IP))

Figure7. $R_{DS(ON)}$ vs Junction Temperature

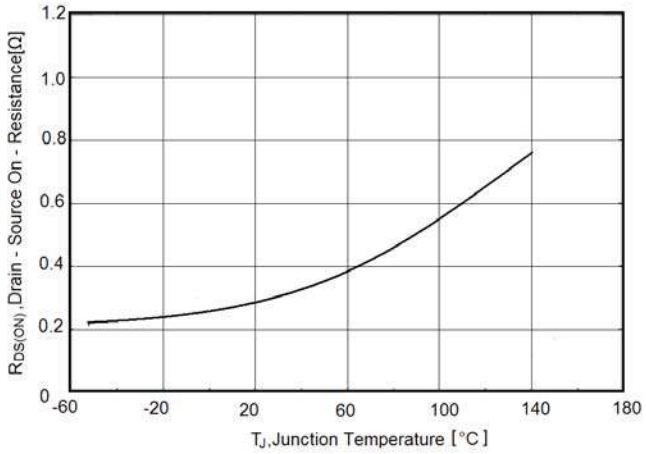


Figure8. BV_{DSS} vs Junction Temperature

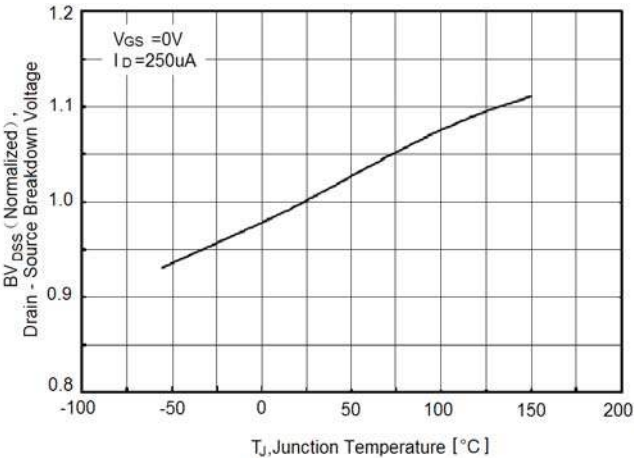


Figure9. Maximum I_D vs Junction Temperature

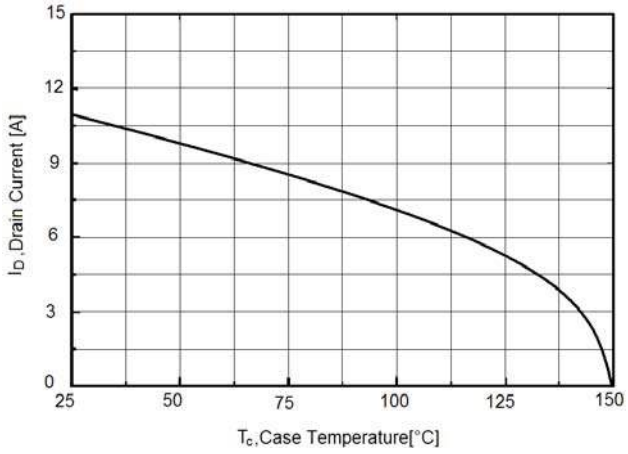


Figure10. Gate charge waveforms

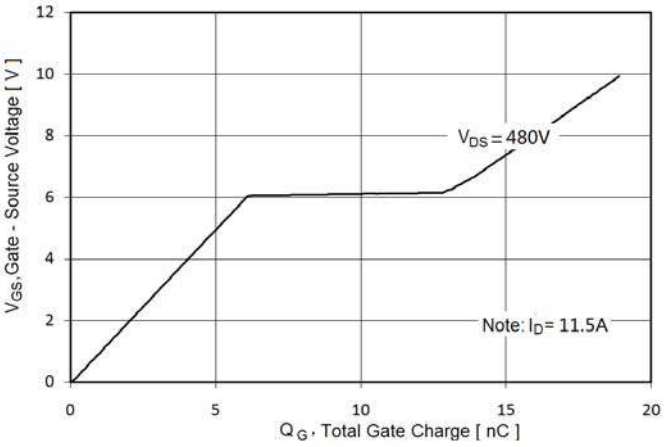
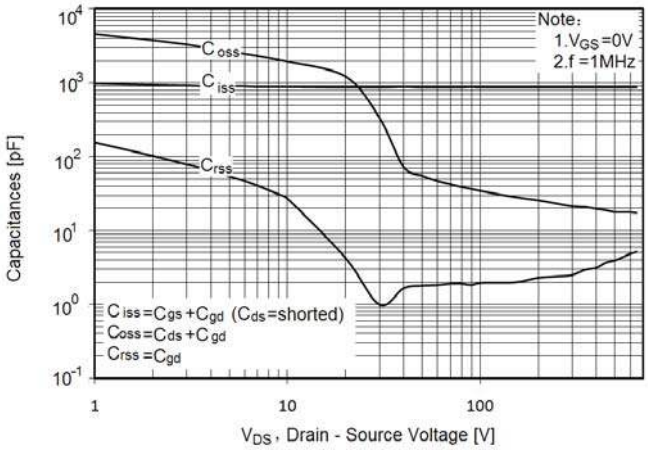
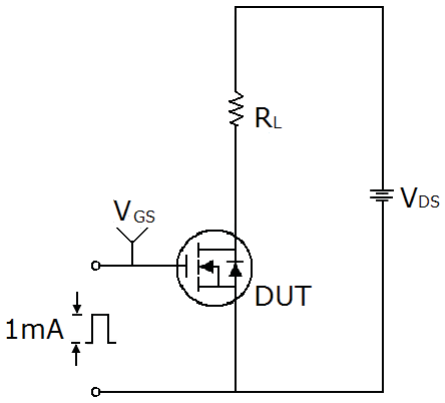


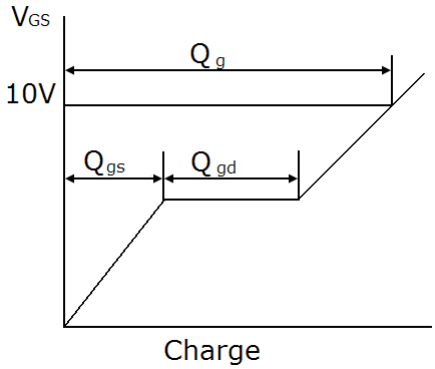
Figure11. Capacitance



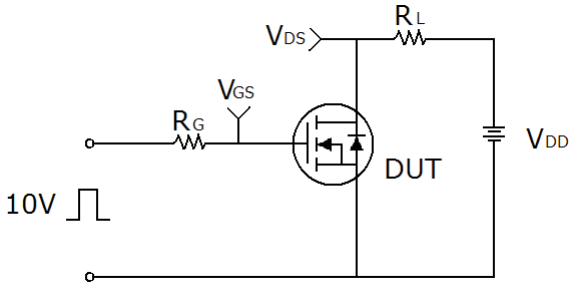
Test circuit

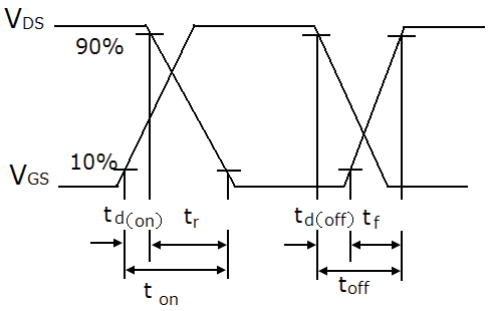
1）Gate charge test circuit & Waveform



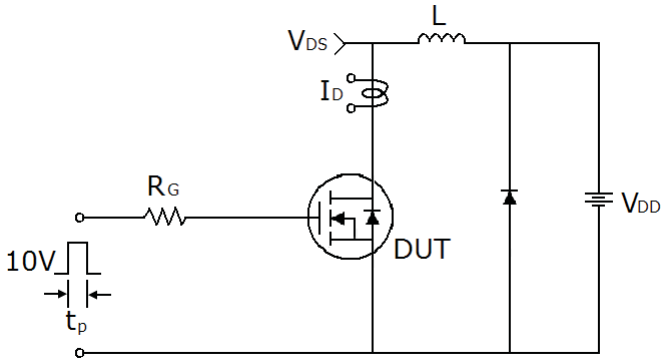


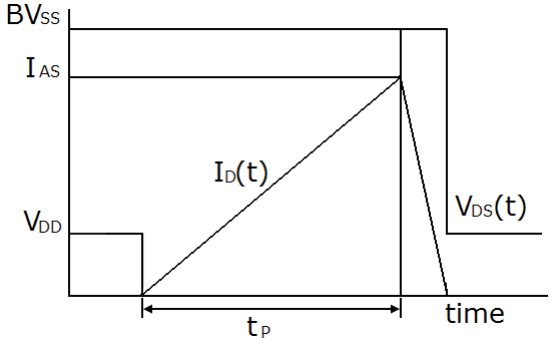
2）Switch Time Test Circuit:



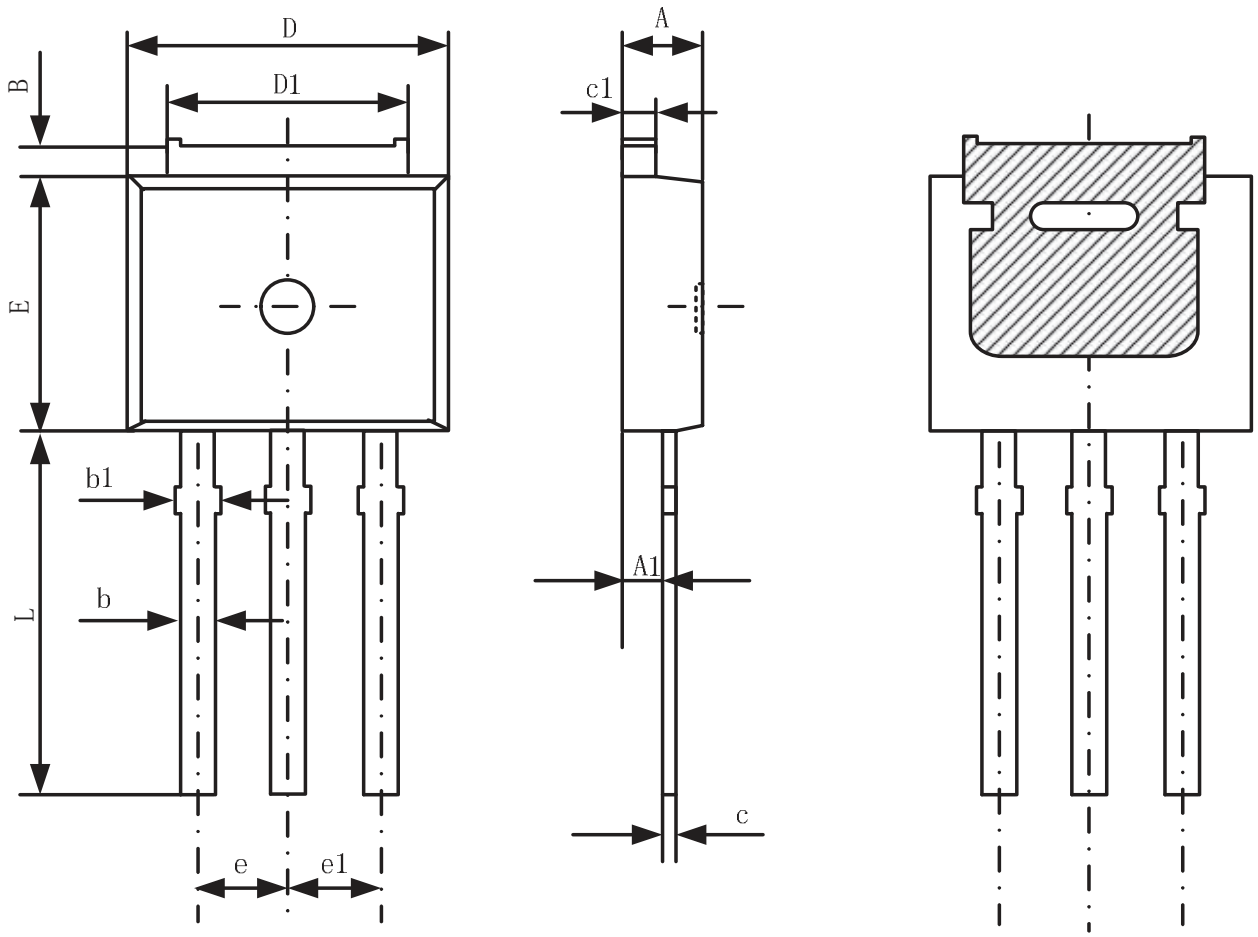


3）Unclamped Inductive Switching Test Circuit & Waveforms



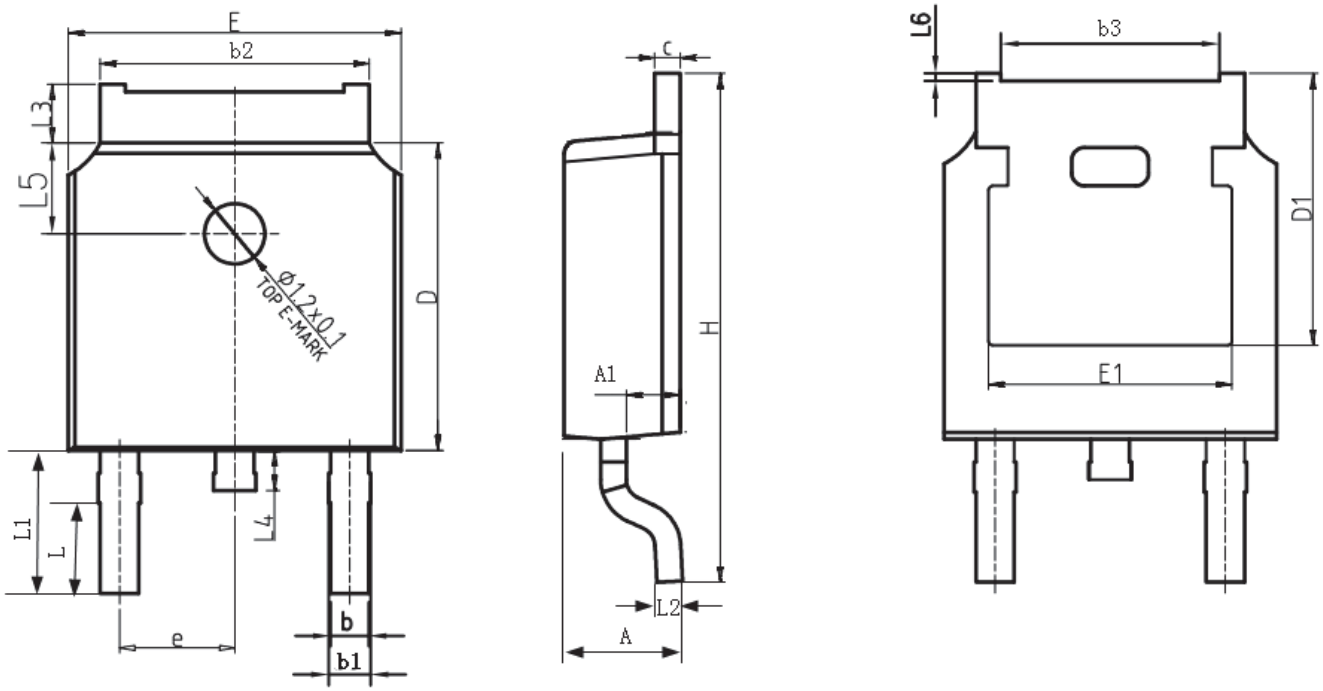


TO-251 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.100	2.500	0.083	0.099
A1	0.850	1.150	0.034	0.045
B	0.718	1.018	0.028	0.040
b	0.700	0.900	0.028	0.036
b1	0.700	1.000	0.028	0.040
c	0.408	0.608	0.016	0.024
c1	0.408	0.508	0.016	0.020
D	6.400	6.800	0.253	0.269
D1	5.180	5.480	0.205	0.217
E	5.950	6.350	0.235	0.251
e	2.286		0.090	
e1	2.286		0.090	
L	6.700	7.300	0.265	0.289

TO-252 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.056	0.061
A1	0.970	1.17	0.025	0.030
b	0.720	0.850	0.018	0.022
b1	0.720	0.930	0.018	0.024
b2	5.230	5.460	0.133	0.139
b3	4.270	4.370	0.108	0.111
c	0.470	0.580	0.012	0.015
D	6.000	6.200	0.152	0.157
D1	5.300 TYP.		0.135	
E	6.500	6.700	0.165	0.170
E1	4.700	4.920	0.119	0.125
e	2.286 TYP		0.058	
L	1.400	1.700	0.036	0.043
L1	2.900 TYP.		0.074	
L2	0.510 TYP.		0.013	
L3	0.900	1.250	0.023	0.032
L4	0.600	1.000	0.015	0.025
L5	1.700	1.900	0.043	0.048
L6	0	0.1223	0.000	0.003

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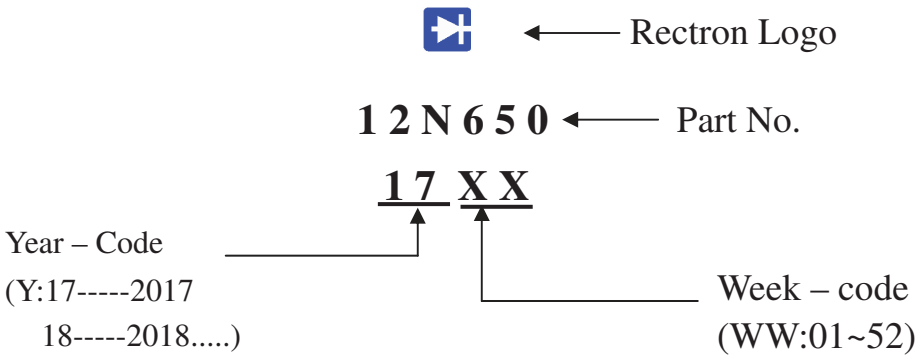
Marking on the body



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